ON Semiconductor

Is Now



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Quad D Flip-Flop With Master Reset

The MC74AC/ACT175 is a high-speed quad D flip-flop. The device is useful for general flip-flop requirements where clock and clear inputs are common. The information on the D inputs is transferred to storage during the LOW-to-HIGH clock transition. The device has a Master Reset to simultaneously clear all flip-flops, when \overline{MR} is low

The MC74AC/ACT175 consists of four edge–triggered D flip–flops with individual D inputs and Q and \overline{Q} outputs. The Clock (CP) and Master Reset (\overline{MR}) are common to all flip–flops. Each D input's state is transferred to the corresponding flip–flop's output following the LOW–to–HIGH Clock (CP) transition. A LOW input to the Master Reset (\overline{MR}) will force all Q outputs LOW and \overline{Q} outputs HIGH independent of Clock or Data inputs. The MC74AC/ACT175 is useful for applications where the Clock and Master Reset are common to all storage elements.

- Outputs Source/Sink 24 mA
- 'ACT175 Has TTL Compatible Inputs

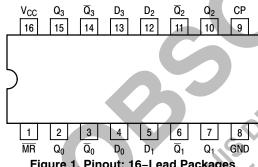


Figure 1. Pinout: 16-Lead Packages (Top View)

PIN ASSIGNMENT

PIN	FUNCTION
D ₀ – D ₃	Data Inputs
CP	Clock Pulse Input
MR	Master Reset Input
Q ₀ – Q ₃	Outputs
$\overline{Q}_0 - \overline{Q}_3$	Outputs



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DIP-16 N SUFFIX CASE 648



SO-16 D SUFFIX CASE 751B



TSSOP-16 DT SUFFIX CASE 948F



EIAJ-16 M SUFFIX CASE 966

ORDERING INFORMATION

Device	Package	Shipping
MC74AC175N	PDIP-16	25 Units/Rail
MC74ACT175N	PDIP-16	25 Units/Rail
MC74AC175D	SOIC-16	48 Units/Rail
MC74ACT175D	SOIC-16	48 Units/Rail
MC74AC175DR2	SOIC-16	2500 Tape & Reel
MC74ACT175DR2	SOIC-16	2500 Tape & Reel
MC74AC175DT	TSSOP-16	96 Units/Rail
MC74ACT175DT	TSSOP-16	96 Units/Rail
MC74AC175DTR2	TSSOP-16	2500 Tape & Reel
MC74ACT175DTR2	TSSOP-16	2500 Tape & Reel
MC74AC175M	EIAJ-16	50 Units/Rail

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 6 of this data sheet.

1

TRUTH TABLE

Inputs			Outputs			
MR	СР	D	Qn	Qn		
L	X	Х	L	Н		
Н		Н	Н	L		
Н		L	L	Н		
Н	L	Х	Qn	Qn		

NOTE: H = HIGH Voltage Level,

L = LOW Voltage Level

X = Immaterial

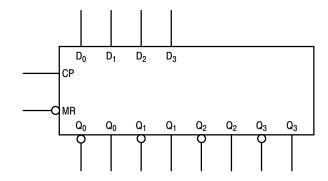
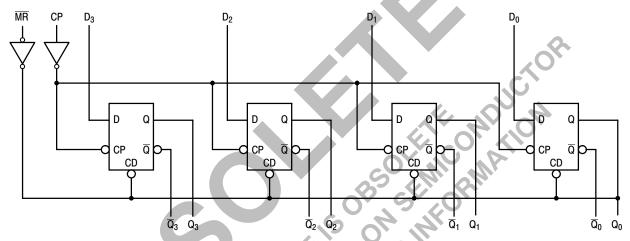


Figure 2. Logic Symbol



NOTE: This diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Figure 3. Logic Diagram

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V _{CC}	DC Supply Voltage (Referenced to GND)	-0.5 to +7.0	V
V _{IN}	DC Input Voltage (Referenced to GND)	-0.5 to V _{CC} + 0.5	V
V _{OUT}	DC Output Voltage (Referenced to GND)	-0.5 to V _{CC} + 0.5	V
I _{IN}	DC Input Current, per Pin	±[2 0	mA
Гоит	DC Output Sink/Source Current, per Pin	±[5 0	mA
Icc	DC V _{CC} or GND Current per Output Pin	±[5 0	mA
T _{stg}	Storage Temperature	-65 to +150	°C

^{*}Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Тур	Min	Unit
V	Complex Vellage	'AC	2.0	5.0	6.0	V
V _{CC}	Supply Voltage	'ACT	4.5	5.0	5.5	V
V _{in} , V _{out}	DC Input Voltage, Output Voltage (Ref. to GND)		0	-	V _{CC}	V
		V _{CC} @ 3.0 V	-	150	-	ns/V
t _r , t _f	Input Rise and Fall Time (Note 1) 'AC Devices except Schmitt Inputs	V _{CC} @ 4.5 V	-	40	-	
	The Bosses except committee inpute	V _{CC} @ 5.5 V	-	25	-	
	Input Rise and Fall Time (Note 2)	V _{CC} @ 4.5 V	-	10	-	A /
t _r , t _f	'ACT Devices except Schmitt Inputs	V _{CC} @ 5.5 V	_	8.0	-	ns/V
TJ	Junction Temperature (PDIP)		77	-	140	°C
T _A	Operating Ambient Temperature Range			25	85	°C
I _{OH}	Output Current - HIGH		-	-	-24	mA
I _{OL}	Output Current - LOW		-	-	24	mA

^{1.} V_{IN} from 30% to 70% V_{CC} ; see individual Data Sheets for devices that differ from the typical input rise and fall times. 2. V_{IN} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

			74	AC	74AC	16.10) *
Symbol	Symbol Parameter		T _A = +25°C		T _A = -40°C to +85°C	Unit	Conditions
			Тур	Guar	anteed Limits		
V _{IH}	Minimum High Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	2.1 3.15 3.85	2.1 3.15 3.85	V	V _{OUT} = 0.1 V or V _{CC} – 0.1 V
V _{IL}	Maximum Low Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	0.9 1.35 1.65	0.9 1.35 1.65	V	V _{OUT} = 0.1 V or V _{CC} – 0.1 V
V _{OH}	Minimum High Level Output Voltage	3.0 4.5 5.5	2.99 4.49 5.49	2.9 4.4 5.4	2.9 4.4 5.4	V	Ι _{ΟUT} = – 50 μΑ
	Output Voltage	3.0 4.5 5.5	- - -	2.56 3.86 4.86	2.46 3.76 4.76	٧	$\begin{tabular}{l} *V_{IN} = V_{IL} \mbox{ or } V_{IH} \\ - 12 \mbox{ mA} \\ I_{OH} - 24 \mbox{ mA} \\ - 24 \mbox{ mA} \\ \end{tabular}$
V _{OL}	Maximum Low Level Output Voltage	3.0 4.5 5.5	0.002 0.001 0.001	0.1 0.1 0.1	0.1 0.1 0.1	V	Ι _{ΟUT} = 50 μΑ
	**	3.0 4.5 5.5	- - -	0.36 0.36 0.36	0.44 0.44 0.44	V	$^{*}V_{IN} = V_{IL} \text{ or } V_{IH}$ 12 mA $I_{OH} \qquad 24 \text{ mA}$ 24 mA
I _{IN}	Maximum Input Leakage Current	5.5		±0.1	±1.0	μΑ	$V_I = V_{CC}$, GND
I _{OLD}	†Minimum Dynamic	5.5	-	-	75	mA	V _{OLD} = 1.65 V Max
I _{OHD}	Output Current	5.5	_	-	-75	mA	V _{OHD} = 3.85 V Min

^{*}All outputs loaded; thresholds on input associated with output under test. \dagger Maximum test duration 2.0 ms, one output loaded at a time.

NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC} .

DC CHARACTERISTICS (continued)

			74AC		74AC			
Symbol	ymbol Parameter (T _A = +25°C		T _A = -40°C to +85°C	Unit	Conditions	
			Тур	Guara	anteed Limits			
I _{CC}	Maximum Quiescent Supply Current	5.5	-	8.0	80	μΑ	V _{IN} = V _{CC} or GND	

^{*}All outputs loaded; thresholds on input associated with output under test.

NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC} .

AC CHARACTERISTICS

				74AC		74	AC		
Symbol	Symbol Parameter			T _A = +25°C C _L = 50 pF			T _A = -40°C to +85°C C _L = 50 pF		Fig. No.
			Min	Тур	Max	Min	Max		
f _{max}	Maximum Clock Frequency	3.3 5.0	149 187	1 1	_	139 187	2	MHz	3–3
t _{PLH}	Propagation Delay CP to \mathbf{Q}_{n} or $\overline{\mathbf{Q}}_{n}$	3.3 5.0	2.0 1.5	-	12.0 9.0	2.0 1.0	13.5 9.5	ns	3–6
t _{PHL}	Propagation Delay CP to \mathbf{Q}_{n} or $\overline{\mathbf{Q}}_{n}$	3.3 5.0	2.5 1.5		13.0 9.5	2.0 1.5	14.5 10.5	ns	3–6
t _{PLH}	Propagation Delay \overline{MR} to \overline{Q}_n	3.3 5.0	3.0 2.0	Š	12.5 9.0	2.5 1.5	13.5 10.0	ns	3–6
t _{PHL}	Propagation Delay MR to Qn	3.3 5.0	3.0 2.0		11.0 8.5	2.5 1.5	12.5 9.0	ns	3–6

AC OPERATING REQUIREMENTS

				74AC	74AC		
Symbol	Parameter S C			ղ = +25°C L = 50 pF	$T_A = -40^{\circ}C$ to +85°C $C_L = 50 \text{ pF}$	Unit	Fig. No.
	1,41,41	V	Тур	Guaranteed	d Minimum		
t _s	Set-up Time, HIGH or LOW D _n to CP	3.3 5.0	1 1	4.5 3.0	4.5 3.0	ns	3–9
t _h	Hold Time, HIGH or LOW D _n to CP	3.3 5.0	1 1	1.0 1.0	1.0 1.0	ns	3–9
t _w	MR Pulse Width Low	3.3 5.0	1 1	4.5 3.5	4.5 3.5	ns	3–6
t _w	CP Pulse Width	3.3 5.0	1 1	4.5 3.5	5.0 3.5	ns	3–6
t _{rec}	Recovery Time MR to CP	3.3 5.0	1 1	0 0	0 0	ns	3–6

^{*}Voltage Range 3.3 V is 3.3 V ± 0.3 V.

[†]Maximum test duration 2.0 ms, one output loaded at a time.

^{*}Voltage Range 5.0 V is 5.0 V ± 0.5 V.

DC CHARACTERISTICS

			74A	СТ	74ACT		
Symbol	Parameter	V _{CC} (V)	T _A = -	+25°C	T _A = -40°C to +85°C	Unit	Conditions
			Тур	Guar	anteed Limits		
V _{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V _{OUT} = 0.1 V or V _{CC} – 0.1 V
V _{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V _{OUT} = 0.1 V or V _{CC} – 0.1 V
V _{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I _{OUT} = – 50 μA
		4.5 5.5	- -	3.86 4.86	3.76 4.76	V	$^{*V}_{IN} = V_{IL} \text{ or } V_{IH} \\ -24 \text{ mA} \\ I_{OH} -24 \text{ mA}$
V _{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I _{OUT} = 50 μA
		4.5 5.5	-	0.36 0.36	0.44 0.44	v C	$^*V_{IN} = V_{IL} \text{ or } V_{IH}$ 24 mA I_{OH} 24 mA
I _{IN}	Maximum Input Leakage Current	5.5	-	±0.1	±1.0	μΑ	$V_I = V_{CC}$, GND
Δl _{CCT}	Additional Max. I _{CC} /Input	5.5	0.6	-	1.5	mA	V _I = V _{CC} - 2.1 V
I _{OLD}	†Minimum Dynamic	5.5	-	0	75	mA	V _{OLD} = 1.65 V Max
I _{OHD}	Output Current	5.5	-	O^{Y} .	-75	mA	V _{OHD} = 3.85 V Min
I _{CC}	Maximum Quiescent Supply Current	5.5	5	8.0	80	μΑ	V _{IN} = V _{CC} or GND

^{*}All outputs loaded; thresholds on input associated with output under test. †Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS

	(9,0)		74ACT			74ACT		Unit	Fig. No.
Symbol	Parameter	V _{CC} * (V)	T _A = +25°C C _L = 50 pF			T _A = -40°C to +85°C C _L = 50 pF			
	0,25		Min	Тур	Max	Min	Max		
f _{max}	Maximum Clock Frequency	5.0	175	-	-	145	-	MHz	3–3
t _{PLH}	Propagation Delay CP to Q _n	5.0	2.0	-	10.0	1.5	11.0	ns	3–6
t _{PHL}	Propagation Delay CP to Q _n	5.0	2.0	_	11.0	1.5	12.0	ns	3–6
t _{PHL}	$\frac{\text{Propagation Delay}}{\overline{\text{MR}} \text{ to } Q_n \text{ or } \overline{Q}_n}$	5.0	2.0	_	9.5	1.5	10.5	ns	3–6

^{*}Voltage Range 5.0 V is 5.0 V ±0.5 V.

AC OPERATING REQUIREMENTS

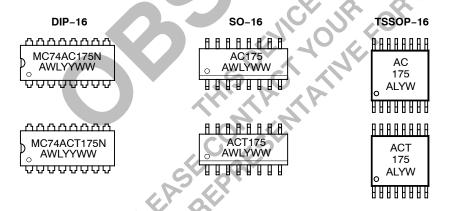
				74ACT	74ACT		
Symbol	Parameter		T,	ղ = +25°C L = 50 pF	T _A = -40°C to +85°C C _L = 50 pF	Unit	Fig. No.
			Тур	Guaranteed	d Minimum		
t _s (H) (L)	Set-up Time, HIGH or LOW D _n to CP	5.0	ı	2.0 2.5	2.0 2.5	ns	3–9
t _h	Hold Time, HIGH or LOW D _n to CP	5.0	-	1.0	1.0	ns	3–9
t _w	MR Pulse Width, LOW	5.0	İ	3.0	4.0	ns	3–6
t _w	CP Pulse Width, HIGH or LOW	5.0	-	3.0	3.5	ns	3–6
t _{rec}	Recovery Time MR to CP	5.0		0	0	ns	3–6

^{*}Voltage Range 5.0 V is 5.0 V ±0.5 V.

CAPACITANCE

Symbol	Parameter	Value Typ	Unit	Test Conditions
C _{IN}	Input Capacitance	4.5	pF	V _{CC} = 5.0 V
C _{PD}	Power Dissipation Capacitance	45.0	pF	V _{CC} = 5.0 V

MARKING DIAGRAMS



WL, L YY, Y = Year WW, W = Work Week 74AC175 ALYW <u>Ŭ U U U U U U U</u>

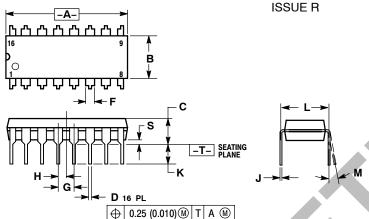
EIAJ-16

= Assembly Location

= Wafer Lot

PACKAGE DIMENSIONS

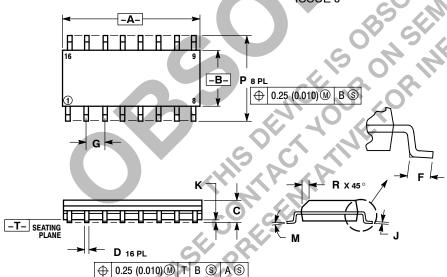
PDIP-16 **N SUFFIX** 16 PIN PLASTIC DIP PACKAGE CASE 648-08



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI
- 714.5M, 1982.
 CONTROLLING DIMENSION: INCH.
 DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL
- DIMENSION B DOES NOT INCLUDE MOLD FLASH.
 ROUNDED CORNERS OPTIONAL.

		INC	HES	MILLIMETERS		
DII	M	MIN	MAX	MIN	MAX	
Α		0.740	0.770	18.80	19.55	
В		0.250	0.270	6.35	6.85	
С		0.145	0.175	3.69	4.44	
D		0.015	0.021	0.39	0.53	
F		0.040	0.70	1.02	1.77	
G		0.100	BSC	2.54 BSC		
Н		0.050	BSC	1.27 BSC		
J		0.008	0.015	0.21	0.38	
K		0.110	0.130	2.80	3.30	
L		0.295	0.305	7.50	7.74	
M		0°	10°	0°	10 °	
S		0.020	0.040	0.51	1.01	

SO-16 **D SUFFIX** 16 PIN PLASTIC SOIC PACKAGE CASE 751B-05 **ISSUE J**



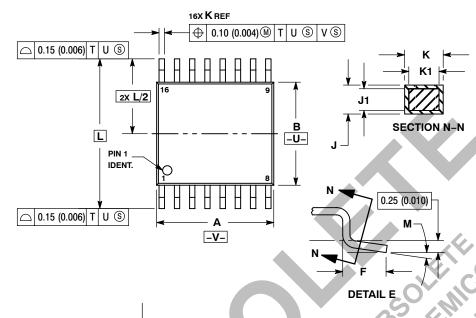
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI
 Y14.5M, 1982. Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER.
 DIMENSIONS A AND B DO NOT INCLUDE

 - MOLD PROTRUSION.
 MAXIMUM MOLD PROTRUSION 0.15 (0.006)
 - PROTRUSION 0.15 (0.006)
 PER SIDE.
 DIMENSION D DOES NOT INCLUDE DAMBAR
 PROTRUSION. ALLOWABLE DAMBAR
 PROTRUSION SHALL BE 0.127 (0.005) TOTAL
 IN EXCESS OF THE D DIMENSION AT
 MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	9.80	10.00	0.386	0.393	
В	3.80	4.00	0.150	0.157	
С	1.35	1.75	0.054	0.068	
D	0.35	0.49	0.014	0.019	
F	0.40	1.25	0.016	0.049	
G	1.27 BSC		0.050 BSC		
J	0.19	0.25	0.008	0.009	
K	0.10	0.25	0.004	0.009	
M	0°	7°	0°	7°	
P	5.80	6.20	0.229	0.244	
R	0.25	0.50	0.010	0.019	

PACKAGE DIMENSIONS

TSSOP-16 **DT SUFFIX** 16 PIN PLASTIC TSSOP PACKAGE CASE948F-01 **ISSUE O**

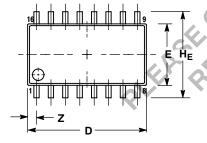


- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI
 - Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETER.
- DIMENSION A DOES NOT INCLUDE MOLD FLASH.
 PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15
- (0.006) PER SIDE.
 DIMENSION B DOES NOT INCLUDE INTERLEAD DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE. DIMENSION K DOES NOT INCLUDE DAMBAR
- DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.

 DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

	MILLIMETERS		INCHES		
DIM	MIN	MAX	MIN	MAX	
A	4.90	5.10	0.193	0.200	
В	4.30	4.50	0.169	0.177	
C		1.20		0.047	
D (0.05	0.15	0.002	0.006	
E	0.50	0.75	0.020	0.030	
G	0.65 BSC		0.026 BSC		
H	0.18	0.28	0.007	0.011	
J	0.09	0.20	0.004	0.008	
J1	0.09	0.16	0.004	0.006	
K	0.19	0.30	0.007	0.012	
K1	0.19	0.25	0.007	0.010	
Ĺ	6.40 BSC		0.252 BSC		
M	0°	8°	0°	8°	



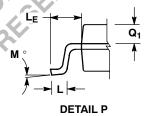


С

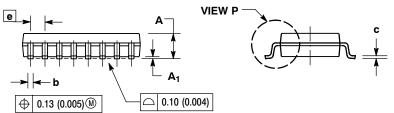
D

☐ 0.10 (0.004)

-T- SEATING PLANE



DETAIL E



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETER.
- DIMENSIONS D AND E DO NOT INCLUDE MOLD
 FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 TERMINAL NUMBERS ARE SHOWN FOR
- REFERENCE ONLY.
 THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION.

 DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE
 BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIMETERS		INCHES		
DIM	MIN	MAX	MIN	MAX	
Α		2.05		0.081	
A ₁	0.05	0.20	0.002	0.008	
b	0.35	0.50	0.014	0.020	
C	0.18	0.27	0.007	0.011	
D	9.90	10.50	0.390	0.413	
Е	5.10	5.45	0.201	0.215	
е	1.27 BSC		0.050 BSC		
ΗE	7.40	8.20	0.291	0.323	
٦	0.50	0.85	0.020	0.033	
LE	1.10	1.50	0.043	0.059	
M	0 °	10 °	0 °	10°	
Q_1	0.70	0.90	0.028	0.035	
Z		0.78		0.031	



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